

October 2, 2019

**Business Segment: ELECTRONICS**

### **MacDermid Alpha Presents Solder Paste Selection for BTC Attach at LEAP Expo in Shenzhen**

(Waterbury, CT USA) – October 2nd, 2019 – The Assembly Division of MacDermid Alpha Electronics Solutions, a world leader in the production of electronics soldering and bonding materials, has been invited to present “**Solder Paste Selection Challenges for Bottom Termination Components (BTC) Attach**” at the session for the EM Asia Innovation Awards Winners 2019 on October 10th, 2019 during the LEAP Expo. This awards presentation is to provide electronics manufacturers with a better understanding of the award-winning products.

ALPHA® OM-358 lead-free, zero-halogen, ultra-low void solder paste won best solder paste materials at the EM Asia Innovation Awards. The paste is designed for ultra-low voiding performance with high reliability alloys such as Innolot as well as traditional SAC alloys and all component types including bottom termination components. Annie Yang, Regional Marketing Manager for MacDermid Alpha Electronics Solutions, will present “Solder Paste Selection Challenges for BTC Attach” which will focus on ways to reduce voiding levels and create more uniform printing deposition by improved formulations. In addition, two solder paste chemistries and several parameters will be evaluated in order to achieve consistent solder paste deposition across the assembly.

Annie will present at 12:00 noon on Thursday, October 10th at the EM Asia Innovation Awards 2019 Event during the LEAP Expo.

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